

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Yasuyuki Ichizono	08/19/2011
Hideki Hirayama	08/19/2011
RECEIVING PARTY DATA	
Name:	Ube Industries, Ltd.
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City:	Ube-shi
State/Country:	JAPAN
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Street Address:	2-1, Hirosawa
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Postal Code:	351-0198
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13203853
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	SPL-11-1297 (309801-020)
NAME OF SUBMITTER:	Leslie Hood
Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif	

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter "ASSIGNOR") by

UBE INDUSTRIES, LTD.

(Insert
ASSIGNEE's
Name(s)
Address(es))

1978-96, Oaza Kogushi, Ube-shi, Yamaguchi 755-8633, Japan

RIKEN

2-1, Hirokawa, Wako-shi, Saitama 351-0198, Japan

(hereinafter "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

Composite Substrate for Formation of Light-Emitting Device,

(Title of
Invention)

Light-Emitting Diode Device and Manufacturing Method Thereof

relating to International Patent Application PCT/JP 2010 / 053727 and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(Insert date
of execution
of application,
if not
concurrent)

(a) executed on _____
(b) filed on August 30, 2011
Serial No. 13 / 203,853

Assignee's attorney is hereby authorized to insert in (b) the specified data, when known.

and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

1) <u>Yasuyuki Ichizono</u> (SIGNATURE)	Yasuyuki Ichizono (TYPE NAME)	August 19, 2011 (DATE)
2) _____ (SIGNATURE)	Hideki Hirayama (TYPE NAME)	_____ (DATE)
3) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
4) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
5) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
6) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
7) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
8) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)

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(Signatures)

Yasuyuki Ichizono

1) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
2) <u>Hideki Hirayama</u> (SIGNATURE)	Hideki Hirayama (TYPE NAME)	August 19, 2011 (DATE)
3) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
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7) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
8) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)

PATENT

RECORDED: 08/30/2011

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